505747550 10/29/2019

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5794363

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
NAM JAE LEE	03/12/2018

RECEIVING PARTY DATA

Name:	SK HYNIX INC.	
Street Address:	2091, GYEONGCHUNG-DAERO, BUBAL-EUB	
City:	ICHEON-SI GYEONGGI-DO	
State/Country: KOREA, REPUBLIC OF		

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16667786

CORRESPONDENCE DATA

Fax Number: (630)323-0335

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Email: uspto.actions@wpapat.com

Correspondent Name: WILLIAM PARK & ASSOCIATES LTD. **Address Line 1:** 930 N. YORK ROAD, SUITE 201

Address Line 4: HINSDALE, ILLINOIS 60521

ATTORNEY DOCKET NUMBER:	PA3427-1C	
NAME OF SUBMITTER:	W. WILLIAM PARK	
SIGNATURE:	/W. William Park/	
DATE SIGNED: 10/29/2019		
This document serves as an Oath/Declaration (37 CFR 1.63).		

Total Attachments: 1

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PATENT 505747550 REEL: 050871 FRAME: 0970

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

[세종, PTPUS201700767]

Title of Invention	SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE SAME			
Declaration	As the below named inventor(s), I hereby declare that: The declaration is directed to: The attached application, or United States application or PCT international application number filed on The above-identified application was made or authorized to be made by me. I believe that I am the original or an original joint inventor of a claimed invention in the application. I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years or both.			
Assignment	NOW, THEREFORE, in consideration of the sum of one dollar (\$1), the receipt whereof is acknowledge, and other good and valuable consideration, I, by these presents do sell, assign and transfer unto said assignee(s) [SK hynix Inc.] [2091, Gyeongchung-daero, Bubal-eub, Icheon-si, Gyeonggi-do, Republic of Korea] and the heirs, successors, assigns and legal representatives of the assignee(s) the full and exclusive right to the said invention in the United States and in its territorial possessions and in any and all foreign countries any and all improvements thereof, the entire rights, title and interest in and to any and all Patents which may be granted therefore in the United States. I hereby authorize and request the Director of the U.S. Patent and Trademark Office to issue said United States Patent to said assignee(s), of the entire right, title, and interest in and to the same, for his sole use and for the use of his legal representatives, to the full end of the term for which said Patent may be granted, as fully and entirely as the same would have been held by me had this assignment and sale not been made. I agree promptly upon request of the assignee(s), its heirs, successors, assigns and legal representatives of the assignee(s) to communicate any facts known to it respecting the patent and the invention set forth therein, and to execute and deliver without further compensation any power of attorney, Assignment, application, whether original, continuation, divisional or reissue, or other papers that may be necessary. I hereby covenant that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale. I further covenant that assignee(s) will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention			
Legal Name Of Inventor	Inventor Name (First Middle LAST):	Nam Jae LEE		
	Inventor Signature: Date:	Nam Jae, Lee		
	Date.	2018 3 12		

☐ A total of 1 supplemental sheet(s) are attached hereto for additional inventors, if any